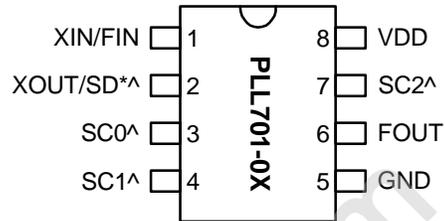


Low EMI Spread Spectrum Multiplier Clock

FEATURES

- Spread Spectrum Clock Generator with selectable multiplier from 1x to 6x outputs.
- Output frequency ranges: 10MHz to 180MHz.
- Modulates external clocks including crystals, crystal oscillators and ceramic resonators.
- Selectable Center Spread Modulation.
- Selectable Modulation rate.
- TTL/CMOS compatible outputs.
- 3.3V Operating Voltage.
- Low short term jitter.
- Available in 8-Pin 150mil SOIC.

PIN CONFIGURATION



XIN/FIN = 10 ~ 30 MHz

Note: ^: Internal pull-up resistor (120kΩ for SD, 30 kΩ for SC0-SC2). *: The value of SD is latched upon power-up. The internal pull-up resistor results in a default high value when no pull-down resistor is connected to this pin (recommended external pull-down resistor of 27 kΩ).

DESCRIPTIONS

The PLL701-01/02/04/06 is a Spread Spectrum Clock Generator designed for the purpose of reducing EMI in high-speed digital systems. Any output frequency from 10 to 180MHz can be selected by programming 6 multiplier modes. The device is designed to operate over a very wide range of input frequencies and provides 1x to 6x modulated clock outputs.

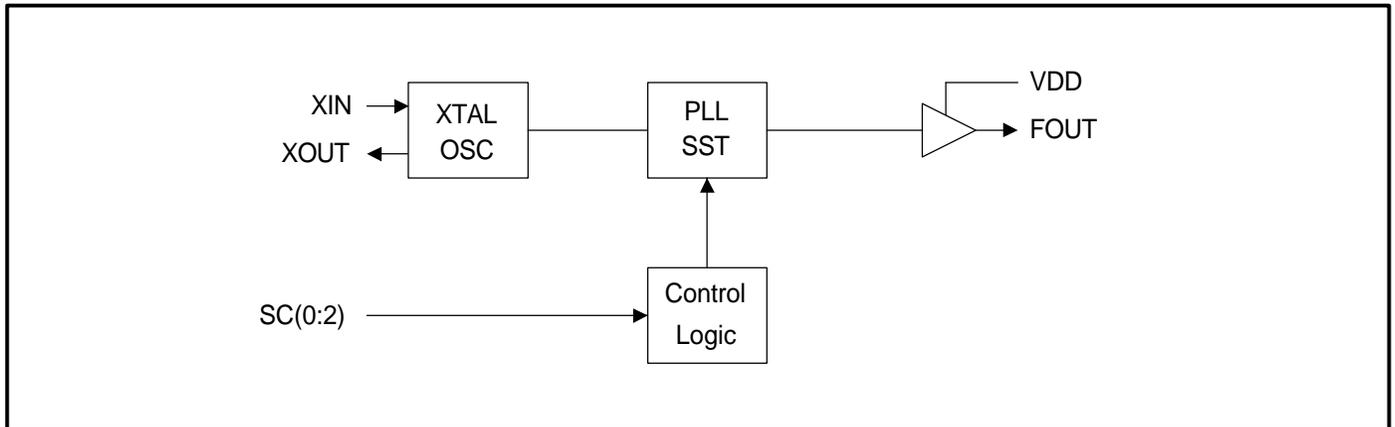
OUTPUT CLOCK (FOUT) SELECTION

SD	SC2	SC1	SC0	FOUT (-01)	FOUT (-02)	FOUT (-04)	FOUT (-06)	SST Modulation					
								Magnitude	Freq.	Type			
1	0	0	0	X1	X2	X4	X6	0.50%	Fin / 512	C	±0.25%		
1	0	0	1	X1	X2	X4	X6			1.00%	D	C	±0.5%
0	0	0	1	X1	X2	X4	X6					1.50%	A
1	0	1	0	X1	X2	X4	X6			2.00%	C		
0	0	1	0	X1	X2	X4	X6					2.50%	A
1	0	1	1	X1	X2	X4	X6			3.00%	C		
0	0	1	1	X1	X2	X4	X6					3.50%	A
1	1	0	0	X1	X2	X4	X6			OFF	C		
0	1	0	0	X1	X2	X4	X6					OFF	A
1	1	0	1	X1	X2	X4	X6			OFF	C		
0	1	0	1	X1	X2	X4	X6					OFF	A
1	1	1	0	X1	X2	X4	X6			OFF	C		
0	1	1	0	X1	X2	X4	X6					OFF	A
1	1	1	1	X1	X2	X4	X6			OFF			

Notes: C: Center Spread. A: Asymmetric Spread. D: Down Spread.

Low EMI Spread Spectrum Multiplier Clock

BLOCK DIAGRAM



PIN DESCRIPTIONS

Name	Number	Type	Description
XIN/FIN	1	I	Crystal input to be connected to fundamental parallel mode crystal.(C _L =18pF) or clock input.
XOUT/SD	2	B	At power-up, this pin is an input pin to select modulation rate. After input sampling, this pin is crystal output. Has internal pull up resistor.
SC0	3	I	Digital control input to select output frequency. Has internal pull-up.
SC1	4	I	Digital control input to select output frequency. Has internal pull-up.
SC2	7	I	Digital control input to select output frequency. Has internal pull-up.
VDD	8	P	3.3V Power Supply.
FOUT	6	O	Modulated Clock Frequency Output. The frequency before modulation is synthesized by multiplying the input frequency by 1X, 2X, 4X, 6X depending on the part number (PLL701-01, -02, -04, -06).
GND	5	P	Ground.

FUNCTIONAL DESCRIPTION

Selectable spread spectrum and modulation rates

The PLL701-01/02/04/06 provides selectable spread spectrum modulation, as well as selectable modulation rate. Selection is made by connecting specific pins to a logical "zero" or "one", according to the output clock selection table and modulation rate selection table on page 1.

In order to reduce the number of pins on the chip, the PLL701-01/02/04/06 uses pin 2 (XOUT/SD) as a bi-directional pin. The pin serves as modulation rate selector input (SD) upon power-up (see modulation rate table on page 1), and as XOUT crystal connection as soon as the input has been latched.

Pins 3 (SC0), 4 (SC1), and 7 (SC2) are used as inputs to select the spread spectrum modulation as shown on the output clock selection table (page 1).

Low EMI Spread Spectrum Multiplier Clock

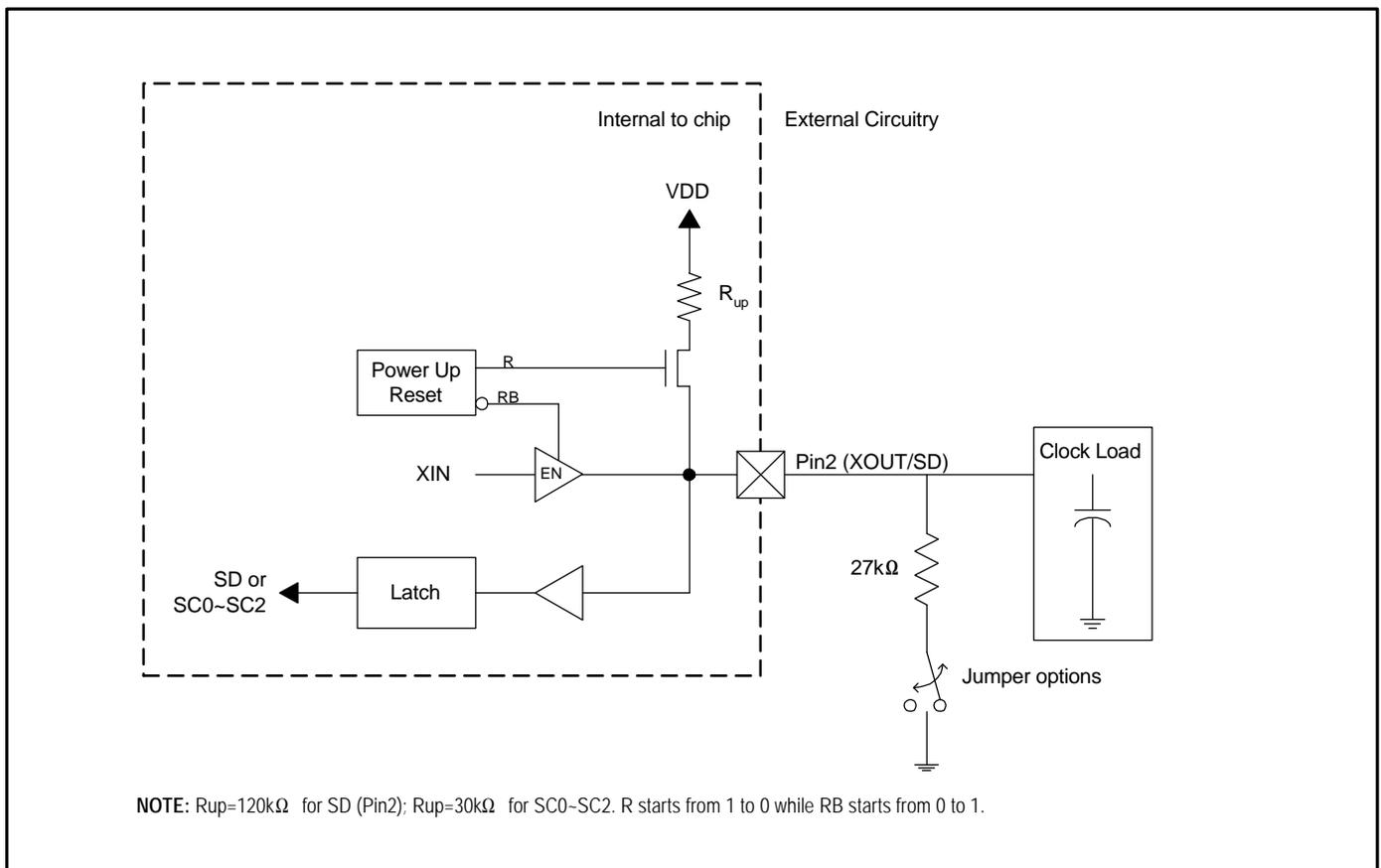
Connecting a selection pin to a logical "one"

All selection pins have an internal pull-up resistor (30kΩ for pins 3, 4, 7, and 120kΩ for pin 2). This internal pull-up resistor will pull the input value to a logical "one" (pull-up) by default, i.e. when no resistive load is connected between the pin and GND. No external pull-up resistor is therefore required for connecting a logical "one" upon power-up.

Connecting a selection pin to a logical "zero"

For an input only pin, i.e. pins 3 (SC0), 4 (SC1), and 7 (SC2), the pin simply needs to be grounded to pull the input down to a logical "zero". Connecting the bi-directional pin (SD) to a logical "zero" will however require the use of an external loading resistor between the pin and GND that has to be sufficiently small (compared to the internal pull-up resistor) so that the pin voltage be pulled below 0.8V (logical "zero"). In order to avoid loading effects when the pin serves as output, the value of the external pull-down resistor should however be kept as large as possible. In general, it is recommended to use an external resistor of around 27kΩ (see Application Diagram).

APPLICATION DIAGRAM FOR OUTPUT AND MODULATION SELECTION



Low EMI Spread Spectrum Multiplier Clock

ELECTRICAL SPECIFICATIONS

1. Absolute Maximum Ratings

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	V_{DD}	$V_{SS}-0.5$	6	V
Input Voltage Range	V_I	$V_{SS}-0.5$	$V_{DD}+0.5$	V
Output Voltage Range	V_O	$V_{SS}-0.5$	$V_{DD}+0.5$	V
Soldering Temperature			260	°C
Storage Temperature	T_S	-65	150	°C
Ambient Operating Temperature*	T_A	-40	85	°C

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

* **Note:** Operating Temperature is guaranteed by design for all parts (COMMERCIAL and INDUSTRIAL), but tested for INDUSTRIAL grade only.

2. DC/AC Specification

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Supply Voltage	V_{DD}		3.15		3.45	V
Input High Voltage	V_{IH}		$0.7 \cdot V_{DD}$			V
Input Low Voltage	V_{IL}				$0.3 \cdot V_{DD}$	V
Input High Current	I_{IH}				100	μA
Input Low Current	I_{IL}				100	μA
Output High Voltage	V_{OH}	$I_{OH}=5mA, V_{DD}=3.3V$	2.4			
Output Low Voltage	V_{OL}	$I_{OL}=6mA, V_{DD}=3.3V$			0.4	
Input Frequency	F_{XIN}	When using a crystal	10		30	MHz
	F_{IN}	When using reference clock	10		30	MHz
Maximum interruption of F_{IN}		When using reference clock			100	μs
Load Capacitance	C_L	Between Pin XIN and XOUT*		18		pF
Pull-up Resistor	R_{up}	PIN 2		120		$k\Omega$
Pull-up Resistor	R_{up}	PIN 3, 4, 7		30		$k\Omega$
Short Circuit Current	I_{sc}			25		mA
3.3V Dynamic Supply Current	I_{CC}	No Load		20		mA

***Note:** Pin XIN and XOUT each has a 36pF capacitance. When used with a XTAL, the two capacitors combined load the crystal with 18pF. If driving XIN with a reference clock signal, the load capacitance will be 36pF (typical).

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3. TIMING CHARACTERISTICS

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Rise Time	T_r	Measured at 0.8V ~ 2.0V @ 3.3V	0.8	0.95	1.1	ns
Fall Time	T_f	Measured at 2.0V ~ 0.8V @ 3.3V	0.78	0.85	0.9	ns
Output Duty Cycle	D_T		45	50	55	%
Cycle to Cycle Jitter	$T_{cyc-cyc}$	FOUT=48MHz @ 3.3V			100	ps
Cycle to Cycle Jitter	$T_{cyc-cyc}$	FOUT=72MHz @ 3.3V			100	ps

Low EMI Spread Spectrum Multiplier Clock

PACKAGE INFORMATION

8 PIN Narrow SOIC (mm)

Symbol	SOIC	
	Min.	Max.
A	1.47	1.73
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	4.95
E	3.80	4.00
H	5.80	6.20
L	0.38	1.27
e	1.27 BSC	

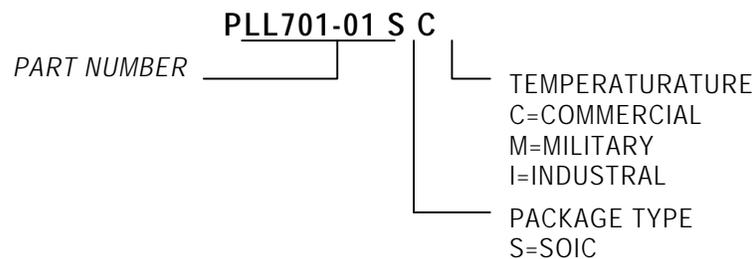
ORDERING INFORMATION

For part ordering, please contact our Sales Department:

47745 Fremont Blvd., Fremont, CA 94538, USA
Tel: (510) 492-0990 Fax: (510) 492-0991

PART NUMBER

The order number for this device is a combination of the following:
Device number, Package type and Operating temperature range



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